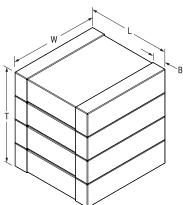


CKC33C224KDGLCTU

Aliases (CKC33C224KDGLC7800)

KONNEKT KC-LINK Comm COG, Ceramic, 0.22 uF, 10%, 1,000 VDC, COG, 4-Chip Standard Orientation.



	Click here for the 3D model.	Typical Compone Notes Chip Size MSL
Dimensions		Specifications
L	9.3mm +/-0.6mm	Capacitance
W	10.2mm +/-0.4mm	Measurement Co
T	10.3mm +/-0.8mm	Tolerance

1.27mm +/-0.4mm

Packaging Specifications	
Packaging	T&R, 180mm
Packaging Quantity	50

В

General Information	
Series	KONNEKT KC-LINK Comm COG
Style	KONNEKT
Description	KC-LINK with KONNEKT, SMD, MLCC, Ultra-Stable, Class I
Features	Ultra-Stable
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	4.3 g
Notes	4-Chip Standard Orientation.
Chip Size	3640-4
MSL	1

Specifications	
Capacitance	0.22 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1,200 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	4.5455 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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